REMARKS

Favorable reconsideration of this application as presently amended and in light of the following discussion is respectfully requested.

Claims 1-16 are presently active in this case, Claims 1 and 2 having been amended and Claim 16 having been newly added by way of the present Amendment.

Consequently, in view of the above discussion, it is respectfully submitted that the present application is in condition for formal allowance and an early and favorable reconsideration of this application is therefore requested.

Respectfully submitted,

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Serial No.: <u>09/646,343</u>

Amendment Filed on: 01-21-03

IN THE CLAIMS

1. (Twice Amended) A film deposition apparatus comprising:

a container forming a processing chamber for processing a target object;

a mounting table which is provided in the processing chamber and on which the target object is mounted;

a first heating apparatus provided in the mounting table[, for heating the target object mounted on the mounting table];

a first gas supply section provided in the container, for supplying processing gas into the processing chamber, the processing gas forming \underline{a} thin film on the target object mounted on the mounting table;

a movable clamp for clamping an edge portion of the target object and holding the target object on the mounting table;

a second heating apparatus formed separately from the [clamp] mounting table to surround the mounting table and arranged [opposite] below the clamp[, for heating] to be opposite the clamp;

a first gas flow path formed between the mounting table and the second heating apparatus;

a <u>second</u> gas flow path formed between the clamp and the second heating apparatus when the clamp is moved to a position where the clamp clamps the target object; and

a second gas supply section for causing backside gas to flow into the [gas flow path] first and second gas flow paths.

2. (Once Amended) The film deposition apparatus according to claim 1, wherein the [gas flow paths extends] first and second gas flow paths extend so as to pass the edge portion of the target object clamped by the clamp [and a periphery of the mounting table].

16. (New)